PRODUCT CHANGE NOTICE

Data Sheet and Wafer Fabrication Site Change for Intersil ISL28288* and ISL28488* Products

Refer to:
PCN11075

Date: July 27, 2011

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To: Our Valued Intersil Customer

Subject: **Data Sheet and Wafer Fabrication Site Change for Intersil Product ISL28288* and ISL28488* –** *NXP Semiconductor Nijmegen, Netherlands*

This notice is to inform you that Intersil has qualified the NXP Semiconductor facility in Nijmegen, the Netherlands for wafer fabrication of the ISL28288* and ISL28488* CQUBIC3 technology products. The change in wafer fabrication site is necessary as the NXP facility in Fishkill, New York has discontinued manufacturing operations. The CQUBIC3 technology wafer fabrication operations have been relocated from the NXP Fishkill to the NXP Nijmegen facility. The data sheet has been updated to align the specification with the characteristics of the product (silicon) fabricated at the NXP Nijmegen facility. As of this notice, the data sheet updates and product qualification activities are complete. The updated data sheet (includes revision history) is available on the Intersil web site at http://www.intersil.com/data/fn/fn6339.pdf.

Products affected:

ISL28288FBZ	ISL28288FUZ-T7	ISL28488FVZ
ISL28288FBZ-T7	ISL28488FAZ	ISL28488FVZ-T7
ISL28288FUZ	ISL28488FAZ-T7	

The NXP Nijmegen facility is ISO 9001:2008 and ISO/TS 16949:2002 certified. The product and site qualification plans are designed using JEDEC and other applicable industry standards to confirm form, fit, function, or interchangeability of the product. A summary of the qualification results is included for reference. The remainder of the manufacturing operations will continue to be processed to previously established conditions and systems. Product affected by this change is identifiable via Intersil's internal traceability system.

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product from either the current or the newly qualified sites and screened to the updated data sheet beginning ninety days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Jon Brewster

Jon Brewster
Intersil Corporation

PCN11075

CC: J. Touvell J. McNamara J. Yun R. Elali D. Goodhew L. Tran P. Lee

PCN11075 – ISL28288/488 Qualification Summary

Legend

Fail	Warning	Pass	QBE	Waived	NA

Reliability Test	EL8200IY fab'ed using CQUBIC3 10 LEAD MSOP using SG600, CRM-1076DJ at UNM Plan Rel: 2010-08-02	ISL28136FBZ fab'ed using CQUICBIC3 8 LEAD SOIC using SG600, A8290 1 Mil Gold at UNM	ISL59837IAZ fab'ed using CQUBIC3 16 LEAD QSOP using SG600, A8290, 1 M GOLD wire at UNM Plan Rel: 2010-08-02
High Temperature Operating Life	SRN090285 Rev 0 0/99 125C 3000hr completed 2010-06-29 disposition=A SRN090285 Rev 1 0/77 125C 3000hr completed 2010-06-29 disposition=A SRN090285 Rev 4 0/44 125C 1000hr completed 2010-03-01 disposition=A SRN090285 Rev 5 0/78 125C 3000hr completed 2010-07-02 disposition=A	SRN100167 Rev 0 0/80 125C 168hr completed 2010-05-26 disposition=A	SRN100060 Rev 0 0/77 125C 3000hr completed 2010-10-05 disposition=A SRN100060 Rev 1 0/78 125C 3000hr completed 2010-10-05 disposition=A
Biased HAST	NA	NA	SRN100060 Rev 1 0/50 130C, 85%RH PRECOND L2 PBFREE 96hr completed 2010-05-25 disposition=A
Storage Life	NA	NA	SRN100060 Rev 1 0/78 150C BAKE AND REFLOW 1000hr completed 2010-07-20 disposition=A

PCN11075 – ISL28288/488 Qualification Summary – cont.

Legend

Fail	Warning	Pass	QBE	Waived	NA

Reliability Test	EL8200IY fab'ed using CQUBIC3 10 LEAD MSOP using SG600, CRM-1076DJ at UNM Plan Rel: 2010-08-02	ISL28136FBZ fab'ed using CQUICBIC3 8 LEAD SOIC using SG600, A8290 1 Mil Gold at UNM	ISL59837IAZ fab'ed using CQUBIC3 16 LEAD QSOP using SG600, A8290, 1 M GOLD wire at UNM Plan Rel: 2010-08-02
Destructive Wire Pull after Storage Life	NA	NA	SRN100060 Rev 0 0/4 completed 2010-02-08 disposition=C
Bond Pull Integrity	NA	SRN100167 Rev 0 0/6 175C 96hr completed 2010-09-16 disposition=C SRN100167 Rev 1 0/5 175C completed 2010-05-13 disposition=C	SRN100060 Rev 0 0/6 175C 96hr completed 2010-05-05 disposition=A SRN100060 Rev 1 0/3 175C completed 2010-02-08 disposition=A SRN100060 Rev 2 0/3 175C completed 2010-02-08 disposition=A
Moisture Sensitivity Classification	MRT09118 MSL=2@260C (Pb Free) Approved=Yes	MRT10062 MSL=3@260C (Pb Free) Approved=Yes	MRT10026 MSL=2@260C (Pb Free) Approved=Yes
Unbiased HAST	SRN090285 Rev 0 0/78 130C, 85%RH PRECOND L2 PBFREE 96hr completed 2009-12-09 disposition=A	SRN100167 Rev 0 0/81 130C, 85%RH PRECOND L2 PBFREE 96hr completed 2010-12-13 disposition=A	NA
Temperature Cycle	SRN090285 Rev 0 0/78 -65C TO 150C PRECOND L2 PBFREE 500cy completed 2009-12-11 disposition=A	SRN100167 Rev 0 0/81 -40C TO 125C PRECOND L2 PBFREE 1000cy completed 2011-01-19 disposition=A	SRN100060 Rev 0 0/78 -40C TO 125C PRECOND L2 PBFREE 1000cy completed 2010-04-27 disposition=A

PCN11075 – ISL28288/488 Qualification Summary – cont.

Legend

Fail	Warning	Pass	QBE	Waived	NA

Reliability Test	EL8200IY fab'ed using CQUBIC3 10 LEAD MSOP using SG600, CRM-1076DJ at UNM Plan Rel: 2010-08-02	ISL28136FBZ fab'ed using CQUICBIC3 8 LEAD SOIC using SG600, A8290 1 Mil Gold at UNM	ISL59837IAZ fab'ed using CQUBIC3 16 LEAD QSOP using SG600, A8290, 1 M GOLD wire at UNM Plan Rel: 2010-08-02
Destructive Wire Pull after Temp Cycle	NA	NA	SRN100060 Rev 0 0/4 completed 2010-06-02 disposition=A
Product Electrical Characterization	Performed by Product Engineering	Perform by Product Engineer	Performed by Product Engineering
ESD Characterization	Performed by Product Engineering HBM: 2500V MM: 400V CDM: 1000V	Perform by Product Eng HBM = 4000V MM = 400V CDM = 2000V	Performed by Product Engineering HBM: 2000V MM: 200V CDM: 1000V
Latch-up Characterization	Performed by Product Engineering latchup Pass Class II Level A	Perform by Product Engineer Latchup Pass Class A Level II	Performed by Product Engineering Latchup Pass Class II Level A